TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2995

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain-source ON resistance : RDS (ON) = $48 \text{ m}\Omega$ (typ.) • High forward transfer admittance : $|Y_{fs}| = 30 \text{ S}$ (typ.)

• Low leakage current : IDSS = $100 \mu A \text{ (max) (VDS} = 250 \text{ V)}$

• Enhancement-mode: $V_{th} = 1.5 \sim 3.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

Maximum Ratings (Ta = 25°C)

Characteristics S		ymbol	Rating	Unit	
Drain-source voltage		V_{DSS}	250	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	250	V	
Gate-source voltage		V _{GSS} ±	20	V	
Drain current	DC (Not e 1)	I _D	30	Α	
	Pulse (Note 1)	I _{DP}	120	Α	
Drain power dissipation	n (Tc = 25°C)	P _D	90	W	
Single pulse avalanche energy (Not e 2)		E _{AS} 925		mJ	
Avalanche current		I _{AR}	30	Α	
Repetitive avalanche energy (Note 3)		E _{AR} 9		mJ	
Channel temperature		T _{ch} 150		°C	
Storage temperature range		T _{stg}	−55~150 °	С	

Unit: mm 15.8 ± 0.5 2.0 1.0 + 0.25 5.45 ± 0.2 3.5 1. GATE 2. DRAIN 3. SOURCE JEDEC JEITA TOSHIBA 2-16F1B

Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics S	ymbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)} 1.	39	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)} 41	. 6	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 50 V, T_{ch} = 25°C (initial), L = 1.74 mH, I_{AR} = 30 A, R_G = 25 Ω

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.

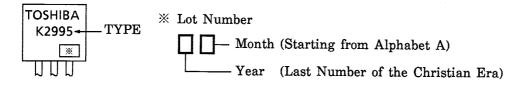
Electrical Characteristics (Ta = 25°C)

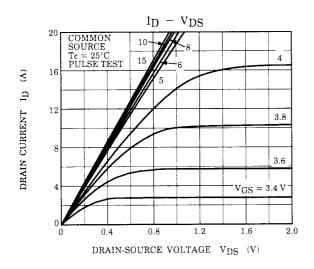
Charac	teristics S	ymbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 250 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source bro	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	250	_	_	V
Gate threshold v	roltage	V _{th}	V _{DS} = 10 V, I _D = 15 A	1.5	_	3.5	V
Drain-source Of	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 15 A	_	48	68	mΩ
Forward transfer	admittance	Y _{fs} V	_{DS} = 10 V, I _D = 15 A	15	30	_	S
Input capacitanc	е	C _{iss} —			5400	_	
Reverse transfer	capacitance	C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	580	_	pF
Output capacitar	nce	Coss			— 1900		
Switching time –	Rise time	t _r —	V_{GS} V_{OV} V_{OUT} V_{OUT} V_{DD} V_{DD}		20	_	- ns
	Turn-on time	t _{on}		_	50	_	
	Fall time	t _f		_	35	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{W}} = 10 \mu s$	— 20	0 —		
Total gate charge (gate-source plus gate-drain)			— 13	2 —			
Gate-source charge		Q _{gs}	$V_{DD} \approx 200 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$		80		nC
Gate-drain ("miller") Charge		Q _{gd}				_	

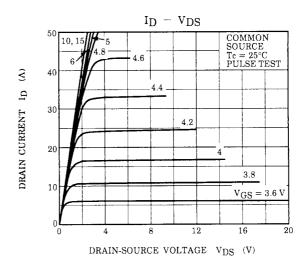
Source-Drain Ratings and Characteristics (Ta = 25°C)

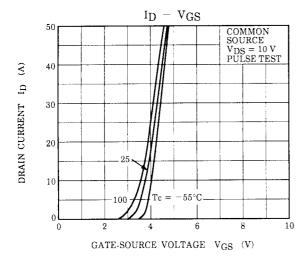
Characteristics S	ymbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Not e 1)	I _{DR} —		1	_	30	Α
Pulse drain reverse current (Not e 1)	I _{DRP} —		_	_	120	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 30 A, V _{GS} = 0 V	_	_	-2.0	V
Reverse recovery time	t _{rr}	I _{DR} = 30 A, V _{GS} = 0 V	1	270	1	ns
Reverse recovery charge	Q_{rr}	dl _{DR} / dt = 100 A / μs	— 3.	0 —		μC

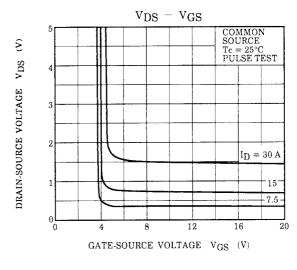
Marking

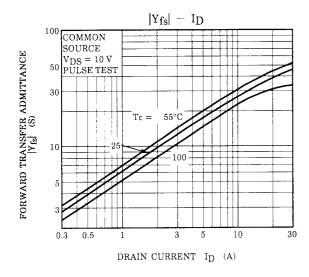


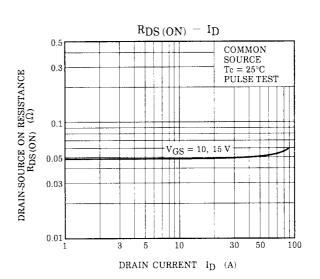




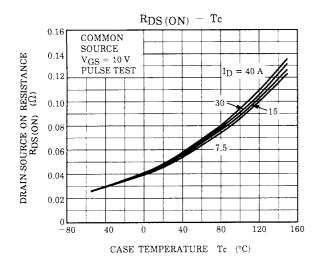


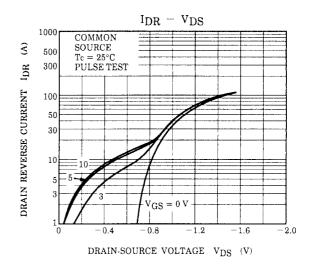


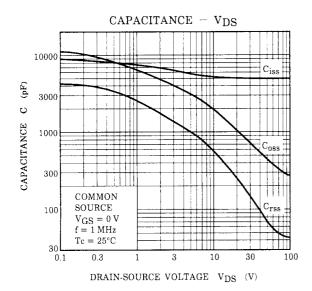


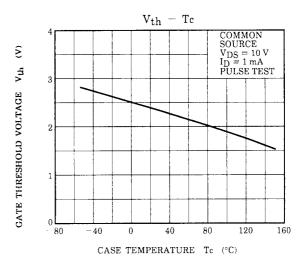


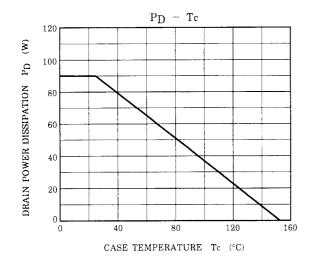
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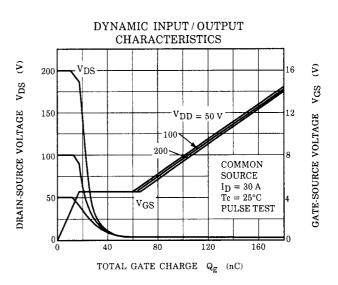




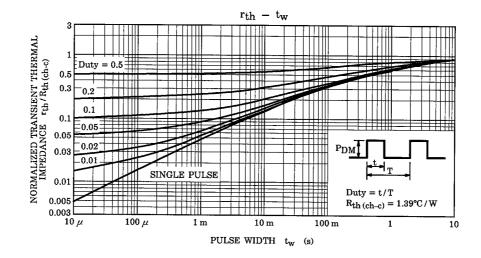


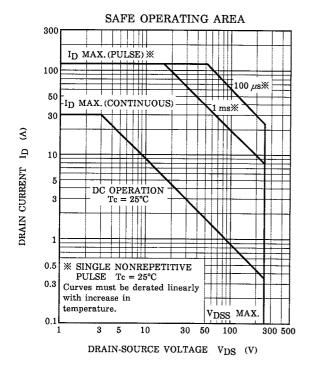


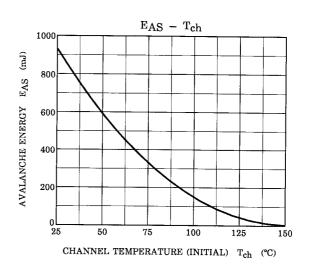


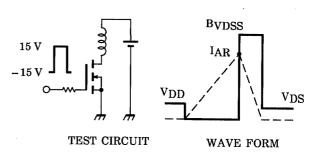


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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 50~V,~L = 1.74~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BV_{DSS}}{BV_{DSS} - V_{DD}} \right) \end{aligned}$$

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